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Author Correction: Effect of FeCoNiCrCu_{0.5} High-entropy-alloy Substrate on Sn Grain Size in Sn-3.0Ag-0.5Cu Solder

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In the Supplementary Information file originally published with this Article, some text was inappropriately used and cited. These errors have been corrected in the Supplementary Information that now accompanies the Article.



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